

TECHNICAL DATA SHEET

PURGE-ATORY Purging Compound

resins such as Delrin & Acetal. Requires no mixing or

Purge-Atory purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for

preparation time. Operating temperatures of 370° - 610°F. Formulated with a SAN resin carrier,



Purge-Atory Purging Compound



food packaging applications. For use with injection molding, extrusion and blow molding.

Unit Package Description 48 and 1,100 pound boxes

Purging Compoud

Generic DescriptionPurging CompoundNet Weight Fill45 & 1,000 pounds

UPC Code 858799000707

Appearance Resin Pellet

Odor None

Applications

Flash Point C >750 degrees >400 degrees

Base Type Resin
Evaporation Rate N/A

HMIS Rating 0, 0, 0, None

DOT Proper Shipping Name Not regulated, Granules, NOI

Removal N/A

Units Per Case 45 & 1,000 pounds

Case Weight (lbs) 45 / 1,000

Working Temperature F 370 to 610 degrees

Working Temperature C 187 to 321 degrees

Propellant N/A

NFPA Aerosol Flammability Level N/A



